

6-2381626-3 ✓ ACTIVE



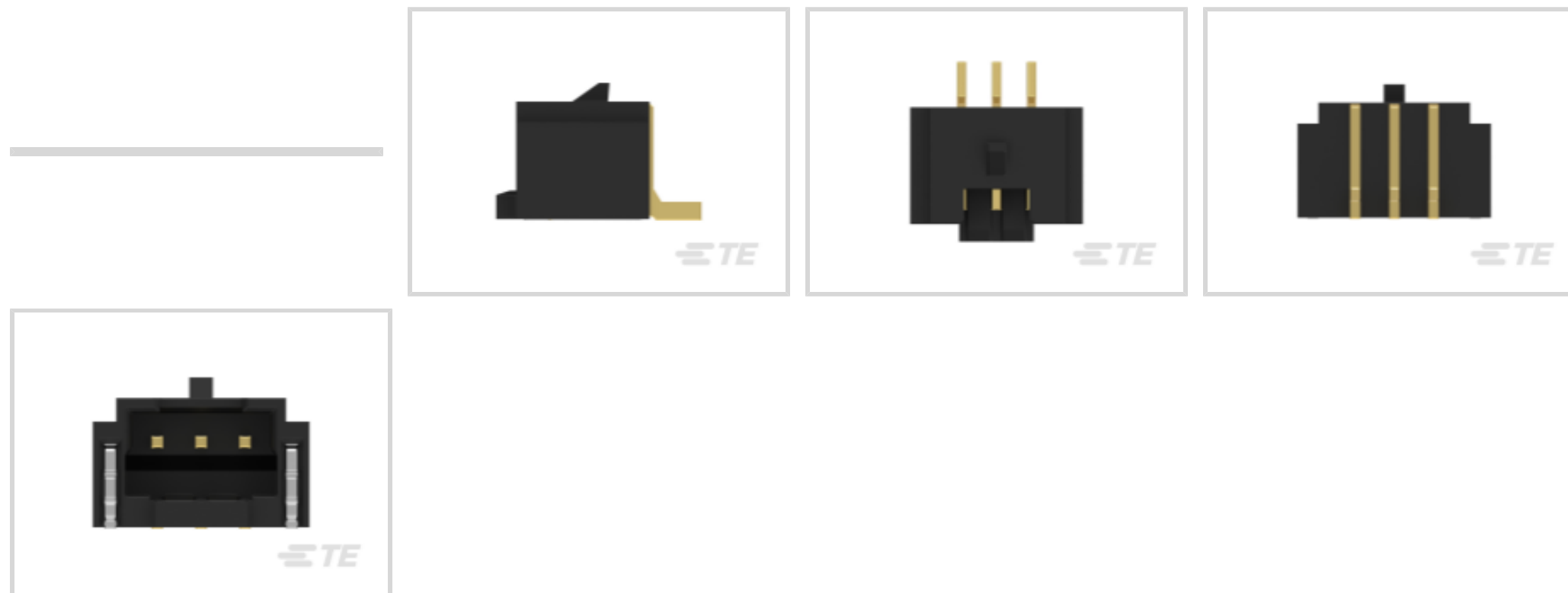
HPI

TE Internal #: 6-2381626-3

HPI, PCB Mount Header, Wire-to-Board, 3 Position, .059 in [1.5 mm]
Centerline, Fully Shrouded, Gold Flash, Surface Mount, Power &
Signal, Black

[View on TE.com >](#)

Connectors > PCB Connectors > PCB Headers & Receptacles



Connector System: **Wire-to-Board**

Number of Positions: **3**

Number of Rows: **1**

Centerline (Pitch): **1.5 mm [.059 in]**

Termination Method to Printed Circuit Board: **Surface Mount**

Features

Product Type Features

| | |
|-----------------------------------|-----------------------|
| Connector System | Wire-to-Board |
| Header Type | Fully Shrouded |
| Sealable | No |
| Connector & Contact Terminates To | Printed Circuit Board |
| PCB Connector Assembly Type | PCB Mount Header |

Configuration Features

| | |
|---------------------|---|
| Number of Positions | 3 |
| Number of Rows | 1 |

Electrical Characteristics

| | |
|---------------------------------------|-----------------|
| Termination Resistance | 20 m Ω |
| Insulation Resistance | 1000 M Ω |
| Dielectric Withstanding Voltage (Max) | 500 V |

Body Features

| | |
|-----------------------|-------|
| Primary Product Color | Black |
|-----------------------|-------|



Contact Features

| | |
|---|-----------------------------|
| Contact Layout | Staggered |
| Contact Underplating Material Thickness | 1.27 – 2.7 µm[50 – 106 µin] |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Gold Flash |
| Contact Base Material | Brass |
| Contact Mating Area Plating Material | Gold Flash |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |

Termination Features

| | |
|---|---------------|
| Termination Method to Printed Circuit Board | Surface Mount |
|---|---------------|

Mechanical Attachment

| | |
|--------------------------|--------------|
| Mating Alignment Type | Polarization |
| Mating Retention | With |
| PCB Mount Retention Type | Solder Peg |
| Mating Retention Type | Latch |
| Connector Mounting Type | Board Mount |
| Mating Alignment | With |
| PCB Mount Alignment | Without |
| PCB Mount Retention | With |

Housing Features

| | |
|-----------------------|-----------------|
| Mating Entry Location | Side |
| Housing Material | LCP |
| Centerline (Pitch) | 1.5 mm[.059 in] |

Usage Conditions

| | |
|-----------------------------|----------------------------|
| Operating Temperature Range | -40 – 105 °C[-40 – 221 °F] |
|-----------------------------|----------------------------|

Operation/Application

| | |
|--------------------------|----------------------|
| Assembly Process Feature | Pick and Place Cover |
| Circuit Application | Power & Signal |

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|



Packaging Features

| | |
|--------------------|--------------|
| Packaging Quantity | 900 |
| Packaging Type | Carton, Reel |

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

| | |
|---|--|
| EU RoHS Directive 2011/65/EU | Compliant with Exemptions |
| EU ELV Directive 2000/53/EC | Not Yet Reviewed |
| China RoHS 2 Directive MIIT Order No 32, 2016 | Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JAN 2022 (223) Candidate List Declared Against: JUL 2021 (219) SVHC > Threshold: Pb (4% in Component Part) Article Safe Usage Statements: Do not eat, drink or smoke when using this product. Wash thoroughly after handling. Recycle if possible and dispose of the article by following all applicable governmental regulations relevant to your geographic location. |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Not reviewed for solder process capability |

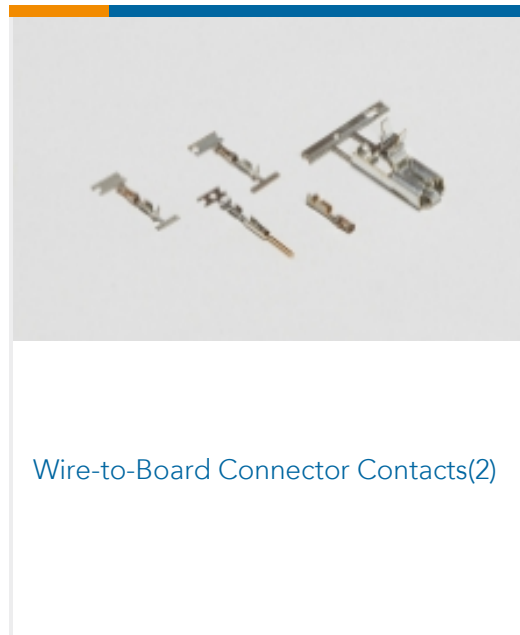
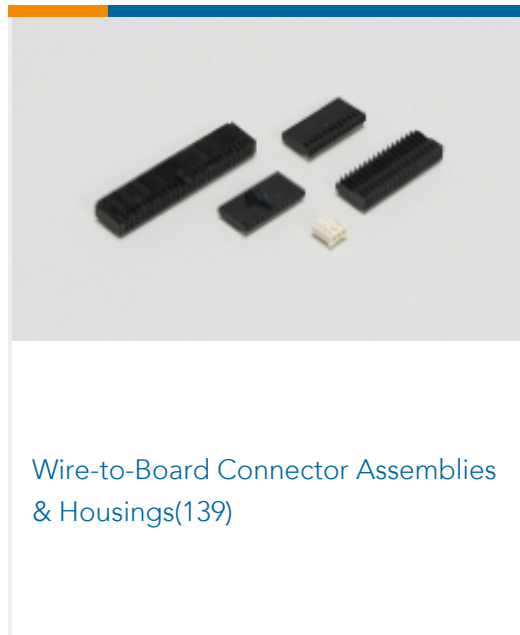
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

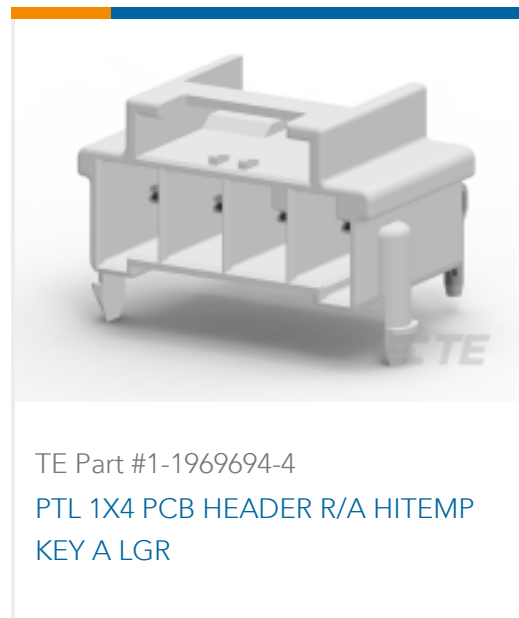
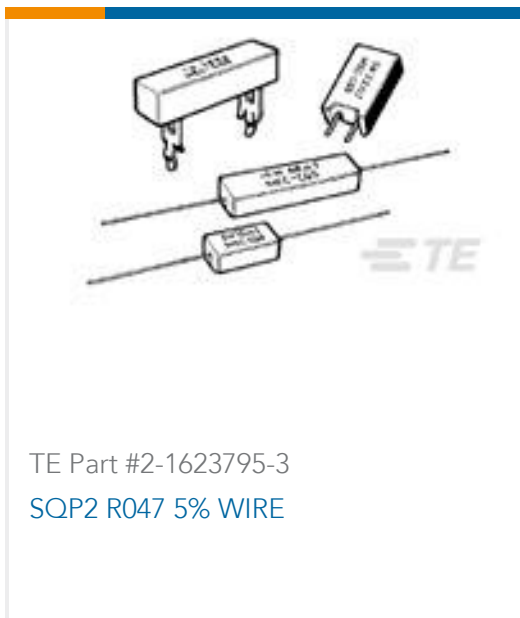
Compatible Parts



Also in the Series | HPI



Customers Also Bought





Documents

Product Drawings

[1.5P 3POS WTB R/A BRD W LATCH AU BLACK](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_6-2381626-3_1.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-2381626-3_1.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_6-2381626-3_1.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Product Specifications

[Product Specification](#)

English